

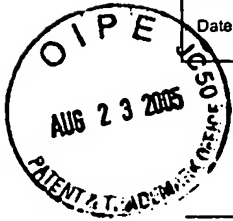
I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as First Class Mail, in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313, on the date shown below.

Dated: August 23, 2005

Signature:

Jean Bova

Ref.: 7452-105/10313554
(PATENT)



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Shih-Ping Hsu

Confirmation No.: 6002

Application No.: 10/695,356

Group Art Unit: 2813

Filed: October 27, 2003

Examiner: Nema O. Berezny

For: SEMICONDUCTOR PACKAGE
SUBSTRATE HAVING CONTACT PAD
PROTECTIVE LAYER FORMED THEREON
AND METHOD FOR FABRICATING THE
SAME

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450
Mail Stop: AF

Dear Sir:

In response to the Office Action mailed April 12, 2005, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 5 of this paper.

Do NOT Enter
9/2/05